

ABSTRACT OF THE DISCLOSURE

The invention is a leadframe/stabilizer (35) for use with semiconductor devices. Stabilizer (35) is for stabilizing the space between of lead frame leads (36-39) and improving the lead to lead spacing and to improve lead tip planarity. Stabilizer (35) extends partially along the length of and on each side of said lead frame leads (36-39) and include a die pad mount (40), integral with and forming a part of said stabilizer 35.

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